EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	291	Mold$3 near5 apparatus and substrate and (stiffener or dam)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L2	104	438/120.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L3	631	257/667.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L4	4210	257/787.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L5	3650	257/678.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L6	3670	257/778.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L7	197	(257/e23.001).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L8	161	(257/e23.18).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02

L9	1734	(257/e23.039).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L10	291	Mold$3 near5 apparatus and substrate and (stiffener or dam)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L11	104	438/120.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L12	631	257/667.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L13	4210	257/787.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L14	3650	257/678.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L15	3670	257/778.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L16	197	(257/e23.001).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L17	161	(257/e23.18).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L18	1734	(257/e23.039).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02

L19	32	("4891687" | "5929517" | "5973389" | "6020221" | "6279758" | "6284569" | "6303985" | "6326544" | "6426565" | "6440777" | "6486562" | "6517662" | "6519843" | "6584897" | "6599365" | "6724071").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L20	2	("4710419").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L21	2	("5650593").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L22	11076	spray$3 near3 mold$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L23	326	L22 and semiconductor and substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L24	291	Mold$3 near5 apparatus and substrate and (stiffener or dam)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
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L26	631	257/667.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
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L28	3650	257/678.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L29	3670	257/778.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L30	197	(257/e23.001).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L31	161	(257/e23.18).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L32	1734	(257/e23.039).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L33	291	Mold$3 near5 apparatus and substrate and (stiffener or dam)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
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L35	631	257/667.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02

L36	4210	257/787.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
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L41	1734	(257/e23.039).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L42	32	("4891687" | "5929517" | "5973389" | "6020221" | "6279758" | "6284569" | "6303985" | "6326544" | "6426565" | "6440777" | "6486562" | "6517662" | "6519843" | "6584897" | "6599365" | "6724071").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L43	2	("4710419").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02

L44	2	("5650593").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L45	11076	spray$3 near3 mold $3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L46	326	L45 and semiconductor and substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L47	104	438/120.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L48	631	257/667.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L49	4210	257/787.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L50	3650	257/678.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L51	3670	257/778.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L52	197	(257/e23.001).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L53	161	(257/e23.18).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02

L54	1734	(257/e23.039).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L55	291	Mold$3 near5 apparatus and substrate and (stiffener or dam)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L56	104	438/120.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L57	631	257/667.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L58	4210	257/787.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L59	3650	257/678.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L60	3670	257/778.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L61	197	(257/e23.001).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L62	161	(257/e23.18).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L63	1734	(257/e23.039).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02

L64	32	("4891687" | "5929517" | "5973389" | "6020221" | "6279758" | "6284569" | "6303985" | "6326544" | "6426565" | "6440777" | "6486562" | "6517662" | "6519843" | "6584897" | "6599365" | "6724071").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
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L66	2	("5650593").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L67	11076	spray$3 near3 mold $3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L68	326	L67 and semiconductor and substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L69	291	Mold$3 near5 apparatus and substrate and (stiffener or dam)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L70	104	438/120.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02

L71	631	257/667.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L72	4210	257/787.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L73	3650	257/678.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L74	3670	257/778.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L75	197	(257/e23.001).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L76	161	(257/e23.18).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L77	1734	(257/e23.039).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L78	291	Mold$3 near5 apparatus and substrate and (stiffener or dam)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L79	104	438/120.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L80	631	257/667.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02

L81	4210	257/787.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L82	3650	257/678.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L83	3670	257/778.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
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L86	1734	(257/e23.039).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L87	32	("4891687" | "5929517" | "5973389" | "6020221" | "6279758" | "6284569" | "6303985" | "6326544" | "6426565" | "6440777" | "6486562" | "6517662" | "6519843" | "6584897" | "6599365" | "6724071").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02

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L89	2	("5650593").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L90	11076	spray$3 near3 mold $3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L91	326	L90 and semiconductor and substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L92	291	Mold$3 near5 apparatus and substrate and (stiffener or dam)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02
L93	7	semiconductor and (plastic near2 stiffener) near10 substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/02/01 19:02

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